



Dual N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
30	0.022 at V _{GS} = 10 V	8	7			
30	0.027 at V _{GS} = 4.5 V	7.9	/			

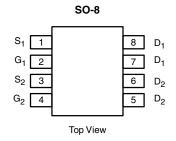
FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

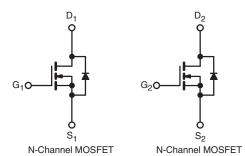


APPLICATIONS

- DC/DC
- Notebook System Power



Ordering Information: Si4804CDY-T1-E3 (Lead (Pb)-free)



Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V_{GS}	± 20	V	
	T _C = 25 °C		8		
Continuous Dunis Comment /T 450 %C)	T _C = 70 °C		7.1		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	7.1 ^{b, c}		
	T _A = 70 °C		5.5 ^{b, c}		
Pulsed Drain Current (10 μs Pulse Width)		I _{DM}	30	А	
Course Dunin Courset Diede Courset	T _C = 25 °C	1	2.4		
Source-Drain Current Diode Current	T _A = 25 °C	l _S	1.8 ^{b, c}		
Pulsed Source-Drain Current		I _{SM}	30		
Single Pulse Avalanche Current Single Pulse Avalanche Energy L = 0.1 mH		I _{AS}	10		
		E _{AS}	5	mJ	
	T _C = 25 °C		3.1		
Mariana Barray Disaination	T _C = 70 °C	Ь	2	W	
Maximum Power Dissipation	T _A = 25 °C	P _D	2 ^{b, c}	VV	
	T _A = 70 °C		1.28 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R_{thJA}	49	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	32	40	J/VV		

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 120 °C/W.

Si4804CDY-T1-E3

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						l	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 050 vA		31		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- I _D = 250 μA		- 5.1			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1.2		2.4	٧	
Gate Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			100	nA	
7. 0. 1/1. 5. 0	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	20			Α	
b	Б	V _{GS} = 10 V, I _D = 7.5 A		0.018	0.022	_	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 6.5 A		0.022	0.027	Ω	
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 7.5 A		20		S	
Dynamic ^a							
Input Capacitance	C _{iss}			865		pF	
Output Capacitance	C _{oss}	N-Channel $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		131			
Reverse Transfer Capacitance	C _{rss}	VDS = 10 V, VGS = 0 V, 1 = 1 WH 12		66			
· ·		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		15.4	23		
Total Gate Charge	Q _g	N. Ohaanad		7	10.5	nC	
Gate-Source Charge	Q_{gs}	N-Channel $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 7.5 \text{ A}$		2.3			
Gate-Drain Charge	Q_{gd}	7 JS = 10 1, 1 GS = 1.0 1, 1 J = 7.0 1		2.2			
Gate Resistance	R_g	f = 1 MHz	0.4	1.9	3.8	Ω	
Turn-On Delay Time	t _{d(on)}			9	18		
Rise Time	t _r	N-Channel $V_{DD} = 15 \text{ V}, R_L = 3 \Omega$		12	24		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_q = 1 \Omega$		17	34		
Fall Time	t _f	D = 0.1, IGEN, I, I, I		9	18		
Turn-On Delay Time	t _{d(on)}			17	34	ns	
Rise Time	t _r	N-Channel $V_{DD} = 15 \text{ V}, R_L = 3 \Omega$		13	26		
Turn-Off Delay Time	t _{d(off)}	$I_{D} \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_{q} = 1 \Omega$		19	35		
Fall Time	t _f			9	18		
Drain-Source Body Diode Characteristi	cs				•		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.4	۸	
Pulse Diode Forward Current ^a	I _{SM}				30	Α	
Body Diode Voltage	V _{SD}	I _S = 1.8 A		0.77	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			16	32	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	N-Channel		8	16	nC	
Reverse Recovery Fall Time	t _a	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		10		ns	
Reverse Recovery Rise Time	t _b	1		6			

Notes:

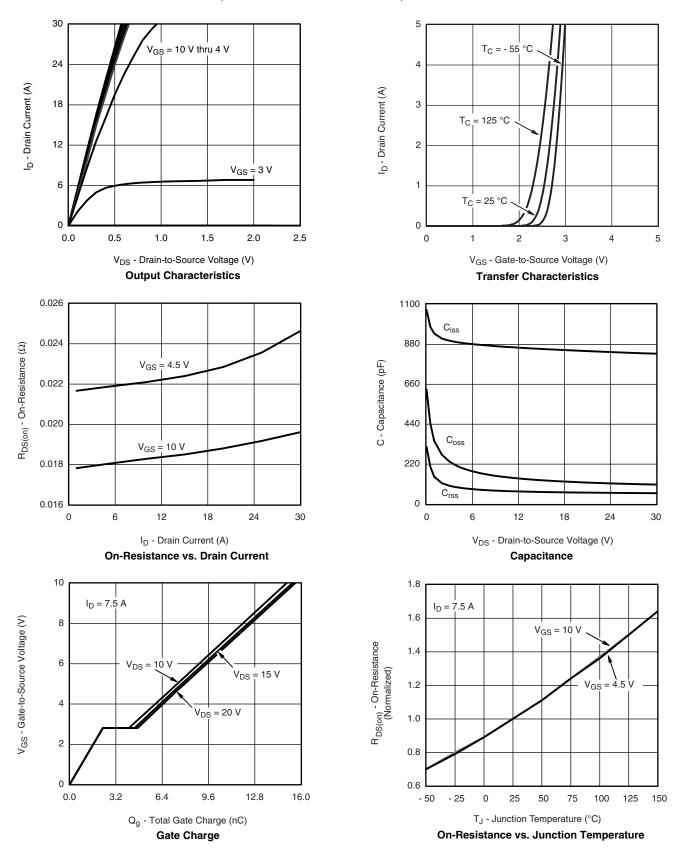
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %

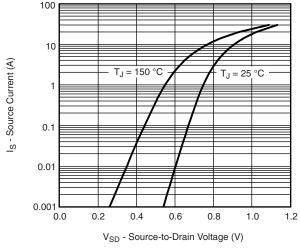


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

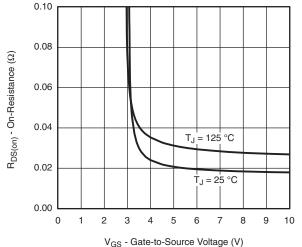


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

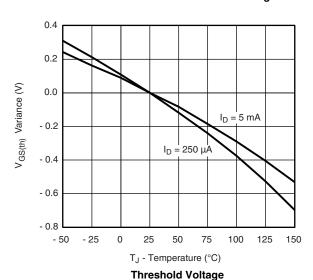


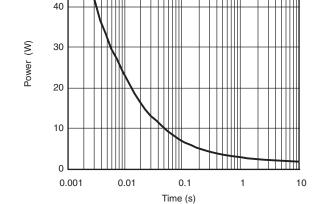
Source-Drain Diode Forward Voltage



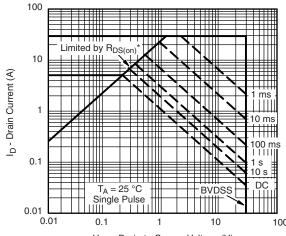
On-Resistance vs. Gate-to-Source Voltage

50





Single Pulse Power, Junction-to-Ambient

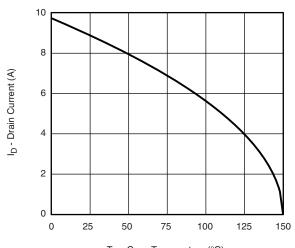


V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

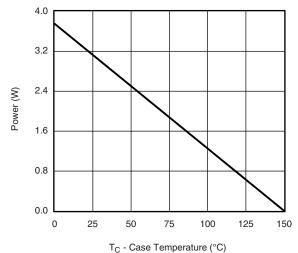


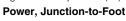
MOSFET TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

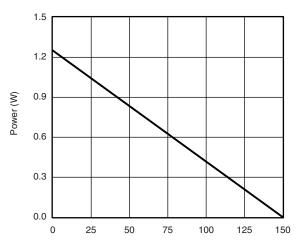


T_C - Case Temperature (°C)

Current Derating*







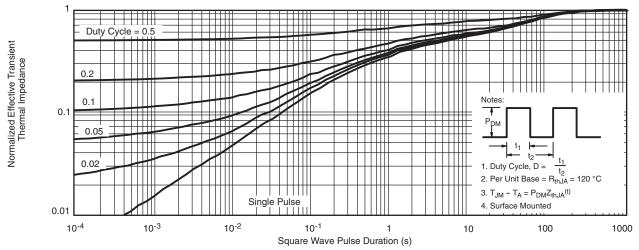
T_A - Ambient Temperature (°C)

Power Derating, Junction-to-Ambient

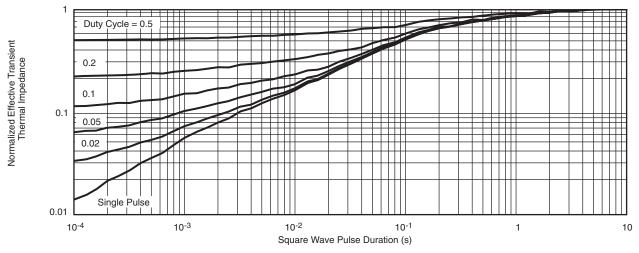
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

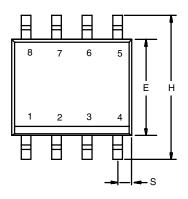


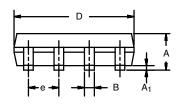
Normalized Thermal Transient Impedance, Junction-to-Foot

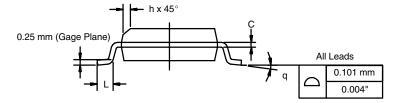
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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

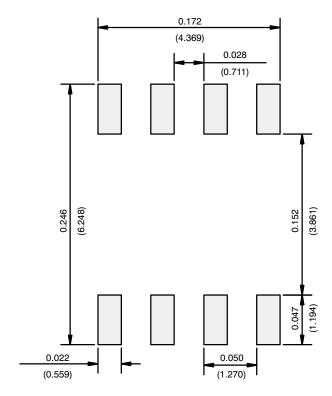
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LON NOTE



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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